

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:0736590002

Status:Active

Overview:hdm

Description:2.00mm (.079") Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm (30µ")

Documents:

3D Model

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

General

Product FamilyBackplane Connectors

Series73659

ApplicationBackplane

CommentsMidplane Power Module

Component TypePower Header

Overviewhdm

Product NameHDM®

StyleN/A

Physical

Circuits (Loaded)12

Circuits (maximum)12

Color - ResinBlack

Durability (mating cycles max)250

First Mate / Last BreakNo

Guide to Mating PartNo

Keying to Mating PartNone

Material - MetalBeryllium Copper

Material - Plating MatingGold

Material - Plating TerminationTin

Material - ResinHigh Temperature Thermoplastic

Number of Columns1

Number of PairsOpen Pin Field

Number of Rows3

OrientationVertical

PC Tail Length (in)0.098 In

PC Tail Length (mm)2.50 mm

PCB LocatorNo

PCB RetentionYes

PCB Thickness Recommended (in)0.098 In

PCB Thickness Recommended (mm)2.50 mm

Packaging TypeTube

Pitch - Mating Interface (in)0.079 In

Pitch - Mating Interface (mm)2.00 mm

Pitch - Term. Interface (in)0.079 In

Pitch - Term. Interface (mm)2.00 mm

Plating min: Mating (µin)30

Plating min: Mating (µm)0.75

Plating min: Termination (µin)150

Plating min: Termination (µm)3.75

Polarized to PCBNo

StackableNo

Surface Mount Compatible (SMC)Yes

Temperature Range - Operating-55°C to +105°C

Termination Interface: StyleThrough Hole

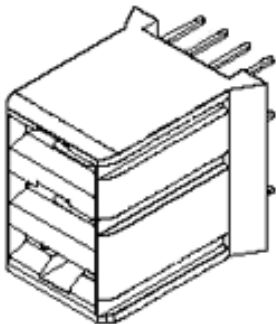


image - Reference only

Series

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73659Series

Mates With

73651 HDM® Board-to-Board Daughterboard Power Module

**Electrical**

|                               |          |
|-------------------------------|----------|
| Current - Maximum per Contact | 15A      |
| Data Rate                     | 1.0 Gbps |
| Real Signals (per 25mm)       | 38       |
| Shielded                      | Yes      |
| Voltage - Maximum             | 500V AC  |

**Solder Process Data**

|                                                |                           |
|------------------------------------------------|---------------------------|
| Duration at Max. Process Temperature (seconds) | 40                        |
| Lead-free Process Capability                   | Reflow Capable (SMT only) |
| Max. Cycles at Max. Process Temperature        | 3                         |
| Process Temperature max. C                     | 260                       |

**Material Info**

**Reference - Drawing Numbers**

|                         |                |
|-------------------------|----------------|
| Packaging Specification | PK-70873-0819  |
| Sales Drawing           | SDA-73659-000* |

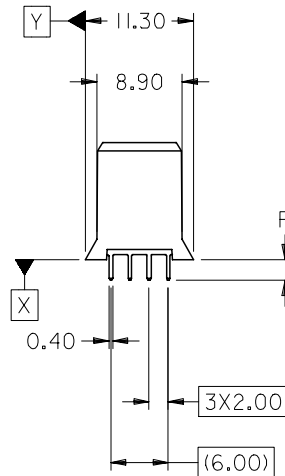
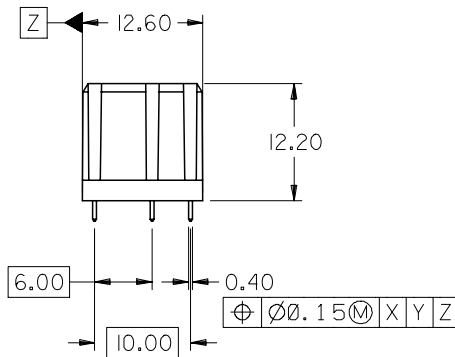
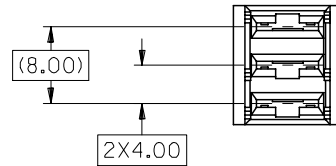
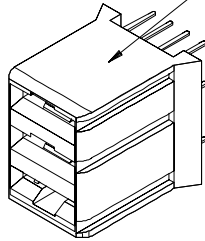
HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

**PLEASE CHECK [WWW.MOLEX.COM](http://WWW.MOLEX.COM) FOR LATEST PART INFORMATION**

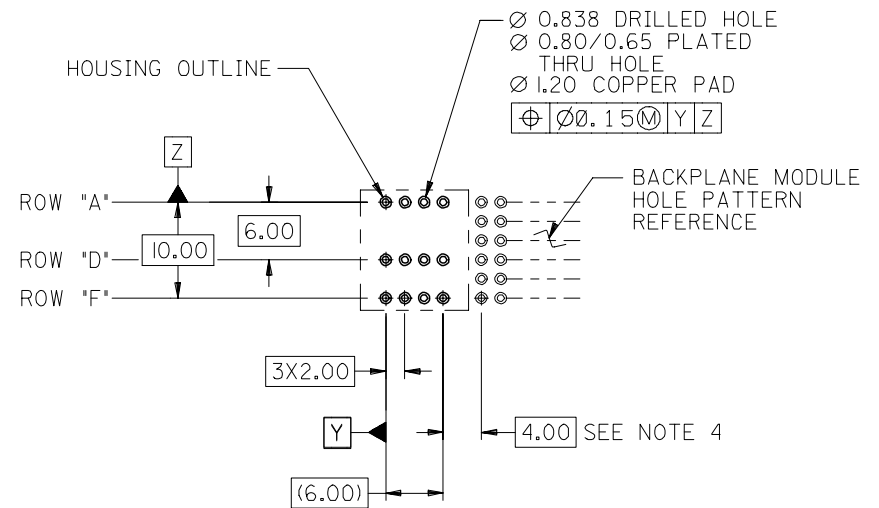
| MATERIAL NUMBER | DIM "P" $\pm 0.25$ |
|-----------------|--------------------|
| 73659-0001      | 2.00               |
| 73659-0002      | 2.50               |
| 73659-0003      | 3.00               |
| 73659-0004      | 3.50               |

DATE CODE AND  
PART NUMBER ON  
THIS SURFACE OR  
SURFACE OPPOSITE.



## NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK  
TERMINAL - BERYLLIUM COPPER
2. FINISH:  
0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA  
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA  
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. THIS DIMENSION MUST BE A MULTIPLE OF 4.00mm.
5. DIMENSION ARE IN MILLIMETERS.



PCB LAYOUT: COMPONENT SIDE  
RECOMMENDED PCB THICKNESS: 1.57 MIN

|                                                                                                                                  |                                                      |                                       |        |                                                                                                                                  |                  |                     |                                                                        |                           |  |  |
|----------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------|---------------------------------------|--------|----------------------------------------------------------------------------------------------------------------------------------|------------------|---------------------|------------------------------------------------------------------------|---------------------------|--|--|
| MODIFY FINISH<br>EC NO: UCP2007-2259<br>2007/03/13<br>DRWN:MSI BARRA<br>2007/03/21<br>CHKD:BBARKER<br>APPR:SMILLER<br>2007/03/22 | QUALITY SYMBOLS<br><br>▽=0<br>▽=0<br><br>DESCRIPTION | GENERAL TOLERANCES (UNLESS SPECIFIED) |        | DIMENSION STYLE<br>MM ONLY                                                                                                       |                  | SCALE<br>2:1        | DESIGN UNITS<br>METRIC                                                 | THIRD ANGLE<br>PROJECTION |  |  |
|                                                                                                                                  |                                                      |                                       | mm     | INCH                                                                                                                             | DRAWN BY<br>REED | DATE<br>1996/12/10  | TITLE<br>SALES ASSY HDM BACKPLANE<br>POWER MODULE WITH<br>SOLDER TAILS |                           |  |  |
|                                                                                                                                  |                                                      | 4 PLACES                              | ± ---  | ± ---                                                                                                                            | CHECKED BY       | DATE                |                                                                        |                           |  |  |
|                                                                                                                                  |                                                      | 3 PLACES                              | ± ---  | ± ---                                                                                                                            | B INGHAM         | 1996/12/10          | MOLEX INCORPORATED                                                     |                           |  |  |
|                                                                                                                                  |                                                      | 2 PLACES                              | ± 0.10 | ± ---                                                                                                                            | APPROVED BY      | DATE                |                                                                        |                           |  |  |
|                                                                                                                                  |                                                      | 1 PLACE                               | ± 0.25 | ± ---                                                                                                                            | B IXLER          | 1996/12/10          | DOCUMENT NO.<br>SDA-73659-000*                                         |                           |  |  |
|                                                                                                                                  |                                                      | ANGULAR ±1/2°                         |        | MATERIAL NO.                                                                                                                     |                  | SHEET NO.<br>1 OF 1 |                                                                        |                           |  |  |
| DRAFT WHERE APPLICABLE<br>MUST REMAIN<br>WITHIN DIMENSIONS                                                                       |                                                      | SIZE<br>B                             |        | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX<br>INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION |                  |                     |                                                                        |                           |  |  |

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9